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U.S. UTILITY Patent Application

APPL NUM 10018708	FILING DATE 04/15/2002	CLASS 451	SUBCLASS 041	GAU 3723	EXAMINER Wilson
**APPLICANTS: Okuda Yuji; Jimbo Naoyuki; Majima Kazutaka; Tsuji Masahiro; Takagi Hideki; Ishikawa Shigeharu; Yasuda Hiroyuki;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/03899 06/15/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 11/168522 06/15/1999 JAPAN 11/168523 06/15/1999 JAPAN 11/185333 06/30/1999					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO P3p2000078US/2369NP		
TITLE : Table of wafer polisher, method of polishing wafer, and method of manufacturing semiconductor wafer					
U.S. DEPT. OF COMM /PAT & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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